

## AMENDMENTS TO THE CLAIMS

### Listing Of Claims

Claims 1-46 (Canceled)

47. (currently amended) A semiconductor component comprising:

a semiconductor die having a face and a plurality of die contacts on the face in a pattern;

~~an electrically insulating layer on the face;~~

a redistribution circuit comprising a plurality of redistribution conductors on the layer face in electrical communication with the die contacts configured to redistribute the pattern of the die contacts into an area array, and a plurality of test contacts in electrical communication with the conductors; and

~~an electrically insulating outer layer on the conductors and the layer having a plurality of openings aligned with selected portions of the conductors configured in an area array; and~~

~~a plurality of bumped contacts in the openings bonded to the selected portions of~~ in the area array in electrical communication with the conductors;

the test contacts configured to permit testing of the die without electrical engagement of the bumped contacts.

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~~the outer layer and the openings configured as a mask for forming the bumped contacts on the selected portions and for preventing bridging between the bumped contacts.~~

48. (currently amended) The component of claim 47 wherein the test contacts comprise portions of the conductors.

~~outer layer comprises a photoimageable material.~~

49. (currently amended) The component of claim 47 wherein the redistribution circuit includes an electrically insulating layer on the conductors.

~~outer layer is patterned to cover selected areas on the face of the die.~~

50. (currently amended) The component of claim 47 wherein the test contacts include non oxidizing layers.

~~a depth of the openings is equal to a thickness of the outer layer minus a thickness of the conductors.~~

51. (currently amended) The component of claim 47 wherein the die has a plurality of edges and the ~~redistribution~~ conductors fan out the pattern of the die contacts to the edges.

52. (currently amended) The component of claim 47 wherein the die has a plurality of edges and the ~~redistribution~~ conductors fan in the pattern of the die contacts from the edges.

Claims 53-67 (canceled)